



Attorney's Docket No.: 082225.P1423D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

Chung Lam

Serial No.: 09/336,116

Filed: June 18, 1999

For: **BOARD LEVEL DECAPSULATOR**

Examiner: Ahmed, S.

Art Group: 1746

8/16
AS
7/3/2

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PRELIMINARY AMENDMENT

Box CPA
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-identified patent application as follows prior to examination of a Continuation Patent Application of the patent application filed on June 18, 1999:

IN THE CLAIMS

Please cancel claims 1-8.

5b1 9. (Amended) A method for decapsulating an integrated circuit (IC) package, comprising:
receiving the IC package installed onto a printed circuit board via one of a through-hole attachment and a surface-mount attachment;
placing the installed IC package onto a tray;
clamping an injection head onto the installed IC package; and,
spraying, via the injection head, decapsulation fluid onto the installed IC package.

5b1 13. (Amended) A method for decapsulating an integrated circuit (IC) package, comprising:
receiving the IC package installed onto a first surface of a printed circuit board, via one of a through-hole attachment and a surface-mount attachment, wherein the printed circuit board includes a second surface located below the first surface of the printed circuit board;
spraying a decapsulation fluid onto the installed IC package via an injection head clamped to the installed IC package, the injection head having a nozzle disposed above the installed IC package that is in fluid communication with an inlet port of said injection head, and a return port that is in fluid communication with an outlet port of the injection head.

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